



## Final Product Change Notification

202312020F01 : S9KEA128 and S9KEA64 Fab Site Expansion From TSMC10 To TSMC11

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Feb 09, 2024 **Effective date:** May 09, 2024

Dear DigiKey Supplier Info PCNs,

Here is your personalized notification about a NXP general announcement.  
For detailed information we invite you to [view this notification online](#)

### Change Category

Wafer Fab Process	Assembly Process	Product Marking	Test Process	Design
Wafer Fab Materials	Assembly Materials	Mechanical Specification	Test Equipment	Errata
Wafer Fab Location	Assembly Location	Packing/Shipping/Labeling	Test Location	Electrical spec./Test coverage
Firmware	Other: Data Sheet update to include TSMC11 fab information			

## PCN Overview

### Description

NXP Semiconductors is announcing the introduction of Taiwan Semiconductor Manufacturing Company Fab 11 (TSMC11), Camas, Washington, USA as a dual source wafer manufacturing location for the S9KEA128 and S9KEA64.

NXP Semiconductors requires the use of flex part numbers to maximize supply continuity. Without the use of flex part numbers, backlog will have to be converted from one fab sourced device to another fab sourced device as capacity dictates.

The Data Sheet for S9KEA128/S9KEA64 has been updated to add the TSMC11 maskset identifier in section 2.3.

The Errata document has also been updated to include TSMC11 mask sets (0P36C/0P37C)

The S9KEA128/S9KEA64 Data Sheet and Errata are attached with this notification and can be found at:

<https://www.nxp.com/products/processors-and-microcontrollers/arm-microcontrollers/automotive-mcus/ultra-reliable-kea-automotive-microcontrollers-mcus-based-on-arm-cortex-m0-plus-core:KEA>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02, SEM-PW-13

### **Reason**

The fab manufacturing site capacity expansion to TSMC11 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original fab (TSMC10).

### **Identification of Affected Products**

Top Side Marking

For S9KEA128, the mask marking for TSMC11 will reflect P37C, while the mask marking for TSMC10 will remain N45K.

For S9KEA64, the mask marking for TSMC11 will reflect P36C, while the mask marking for TSMC10 will remain N22J.

### **Product Availability**

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#### **Sample Information**

Samples are available from Feb 29, 2024

Please see the attachment "S9KEA128\_S9KEA64 TSM10 to TSMC11 Fab Expansion FPCN Supplement.pdf" for sample part numbers.

#### **Production**

Planned first shipment May 10, 2024

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Data Sheet Revision**

A new datasheet will be issued

#### **Disposition of Old Products**

Fab Expansion. No depletion of inventory required.

### **Additional information**

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Self qualification: [view online](#)

Additional documents: [view online](#)

### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 10, 2024.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

<b>Name</b>	Amanda Shearer
<b>Position</b>	Change Management
<b>e-mail address</b>	amanda.shearer@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

### **About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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